

METHOD FOR MANUFACTURING ENCAPSULATED ELECTRONIC COMPONENTS, PARTICULARLY INTEGRATED CIRCUITS

Inventors: Janssen et al.

Docket No: 903-51 CON

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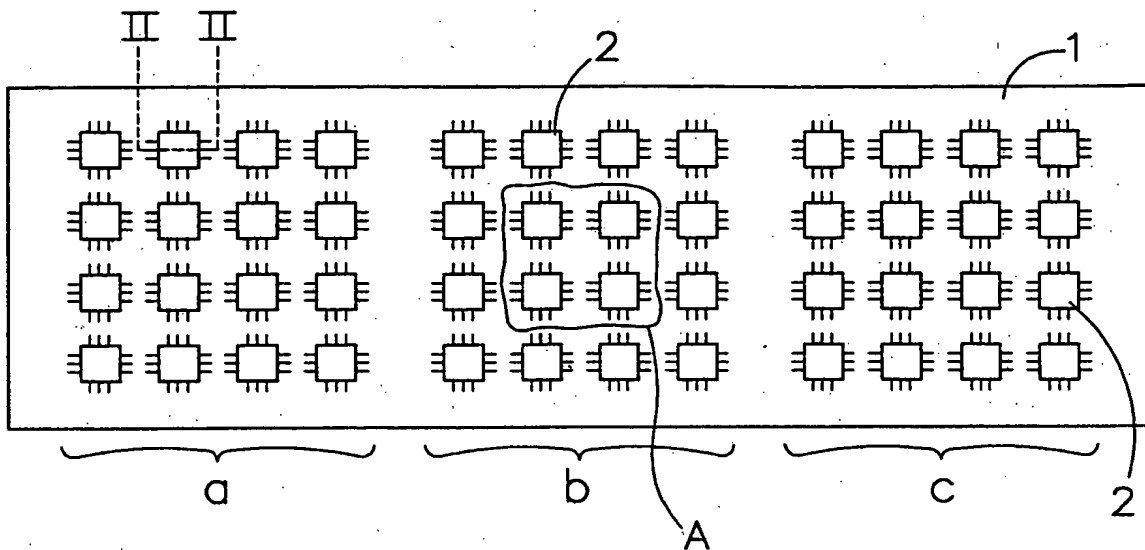


Fig 1

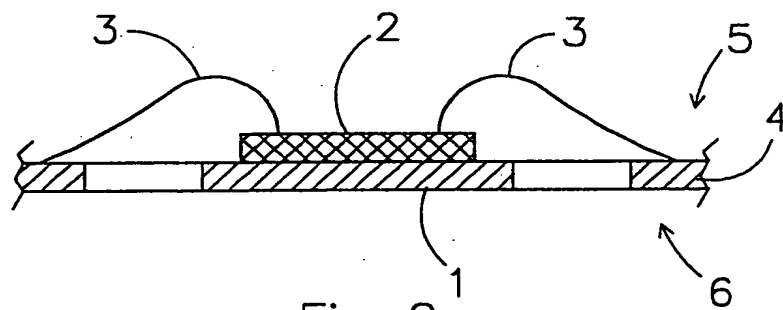


Fig 2

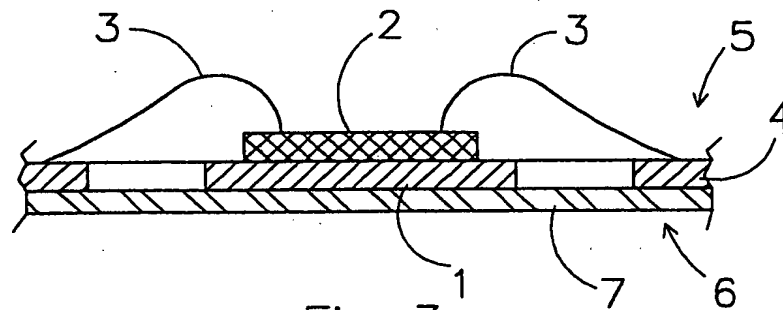


Fig 3

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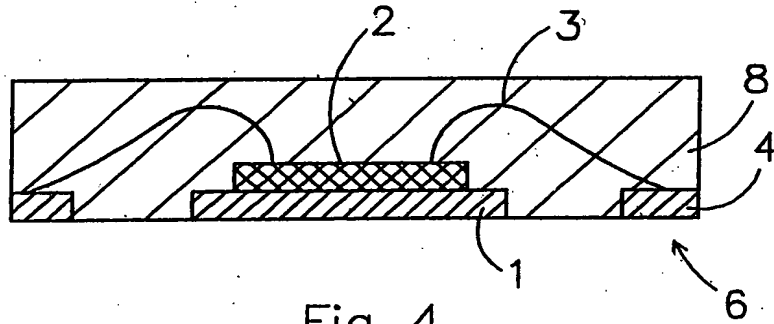


Fig 4

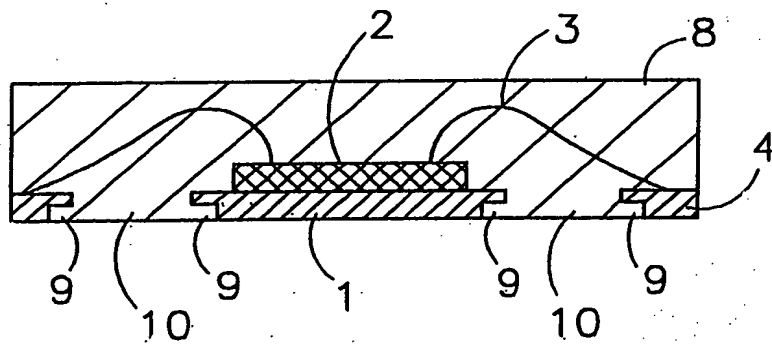


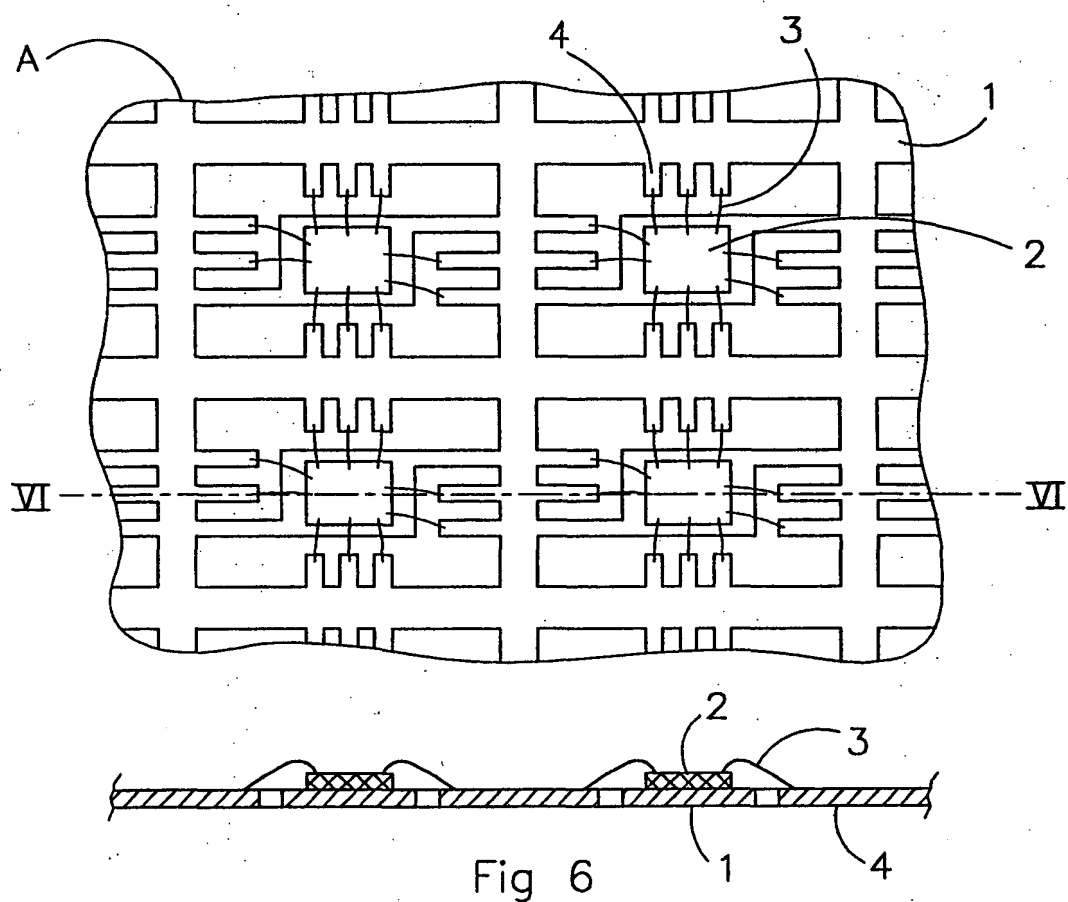
Fig 5

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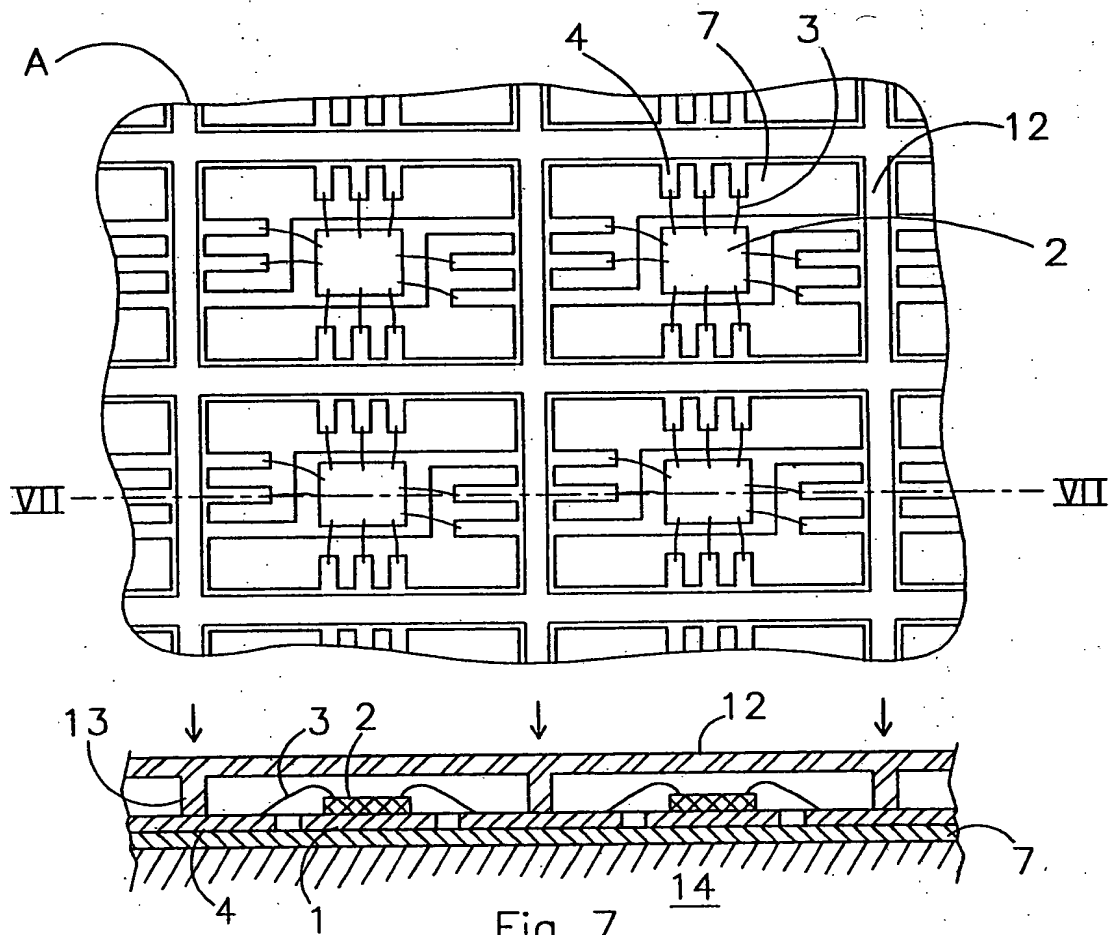


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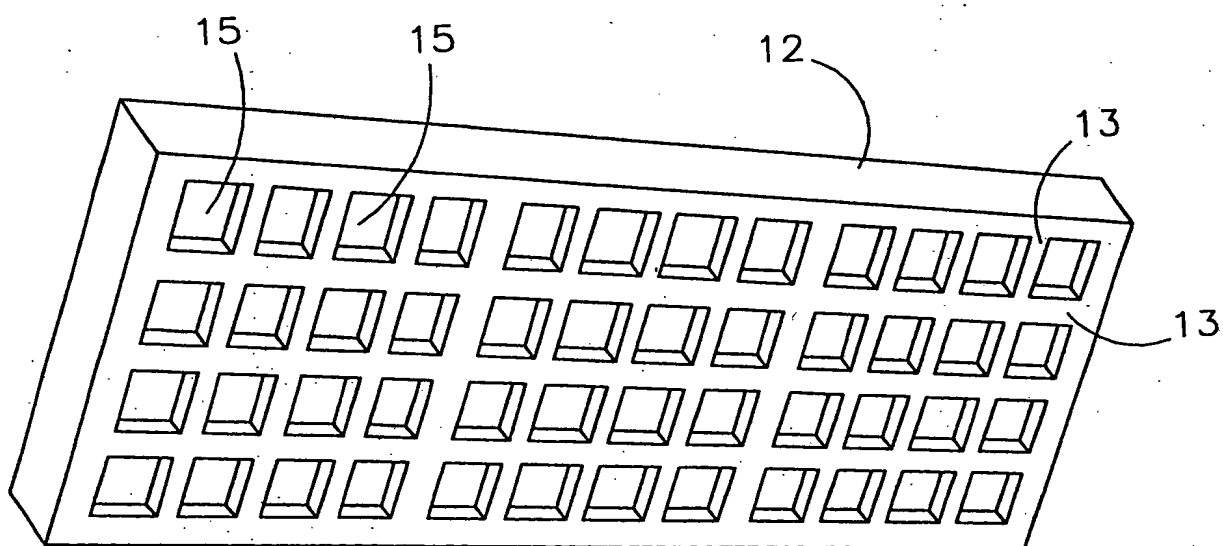


Fig 8

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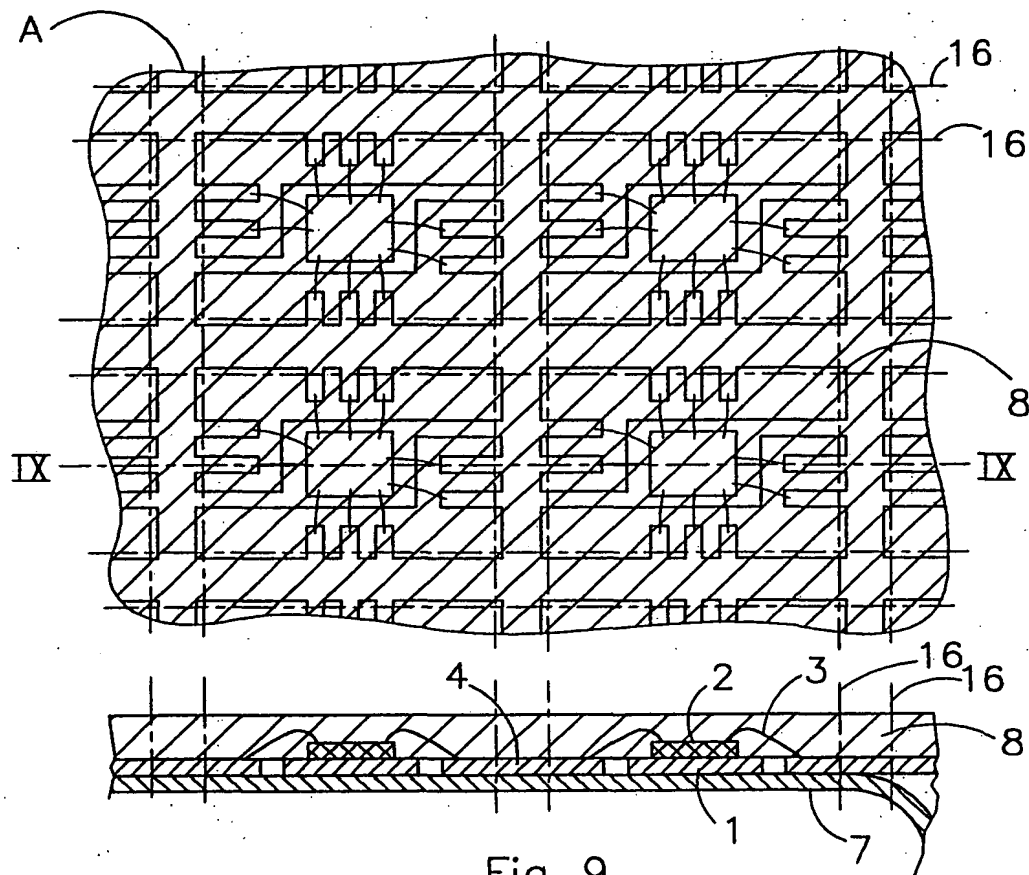


Fig 9